

# HVD372B

## Variable Capacitance Diode for VCO

REJ03G0503-0200

Rev.2.00

Jan 31, 2006

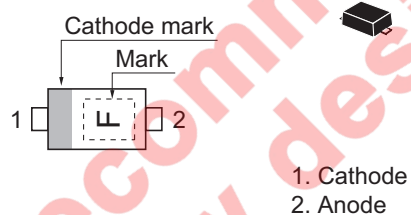
### Features

- High capacitance ratio. ( $n = 2.00$  min)
- Good linearity of C-V curve.
- Super small Flat Lead Package (SFP) is suitable for surface mount design.

### Ordering Information

Type No.	Laser Mark	Package Name	Package Code
HVD372B	F	SFP	PUSF0002ZB-A

### Pin Arrangement



## Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	$V_R$	15	V
Junction temperature	$T_j$	125	°C
Storage temperature	$T_{stg}$	-55 to +125	°C

## Electrical Characteristics

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse current	$I_{R1}$	—	—	10	nA	$V_R = 15\text{ V}$
	$I_{R2}$	—	—	100		$V_R = 15\text{ V}, T_a = 60^\circ\text{C}$
Capacitance	$C_1$	15.0	—	17.0	pF	$V_R = 1\text{ V}, f = 1\text{ MHz}$
	$C_4$	7.00	—	8.50		$V_R = 4\text{ V}, f = 1\text{ MHz}$
Capacitance ratio	n	2.00	—	—	—	$C_1 / C_4$
Series resistance	$r_s$	—	—	0.40	$\Omega$	$V_R = 1\text{ V}, f = 470\text{ MHz}$

Note: For SFP package, the material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

Not recommended  
for new design

## Main Characteristics

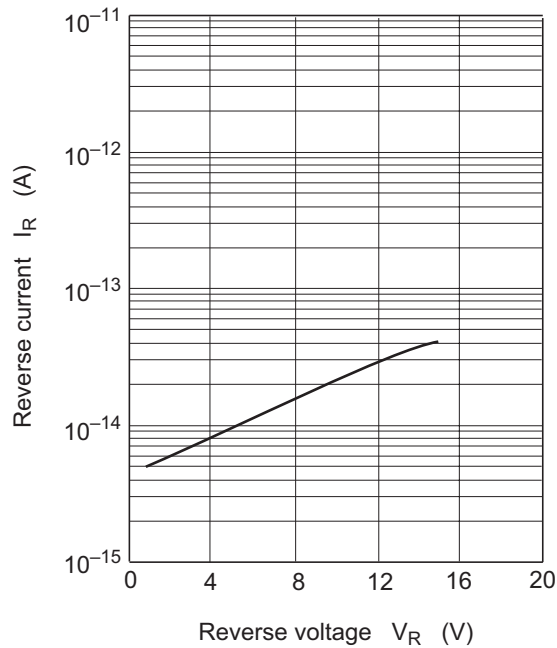


Fig.1 Reverse current vs. Reverse voltage

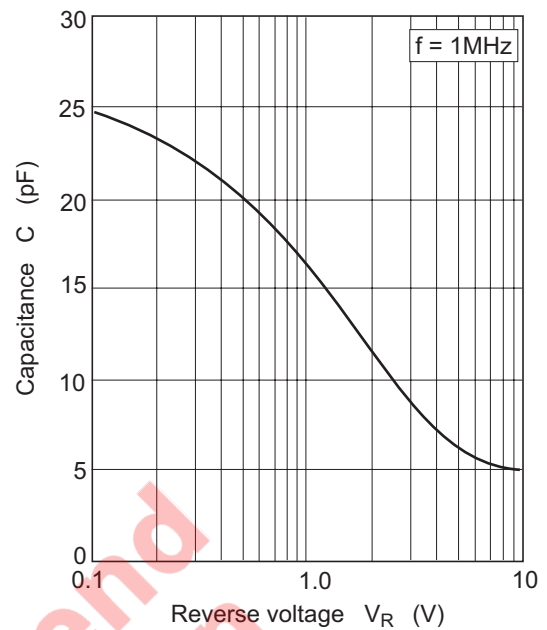


Fig.2 Capacitance vs. Reverse voltage

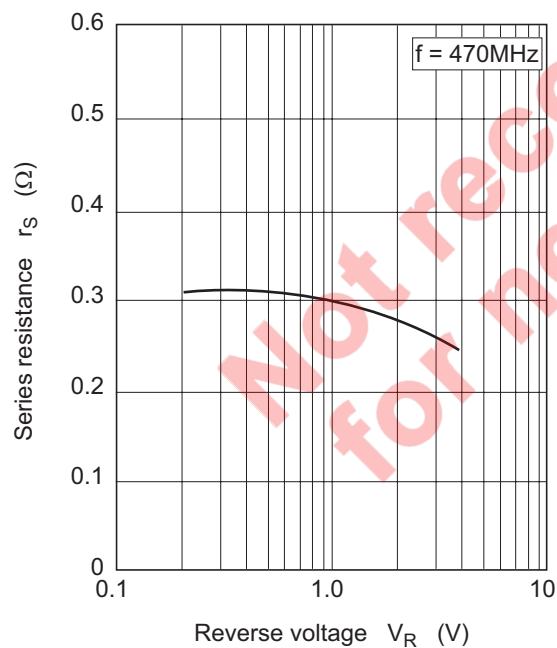
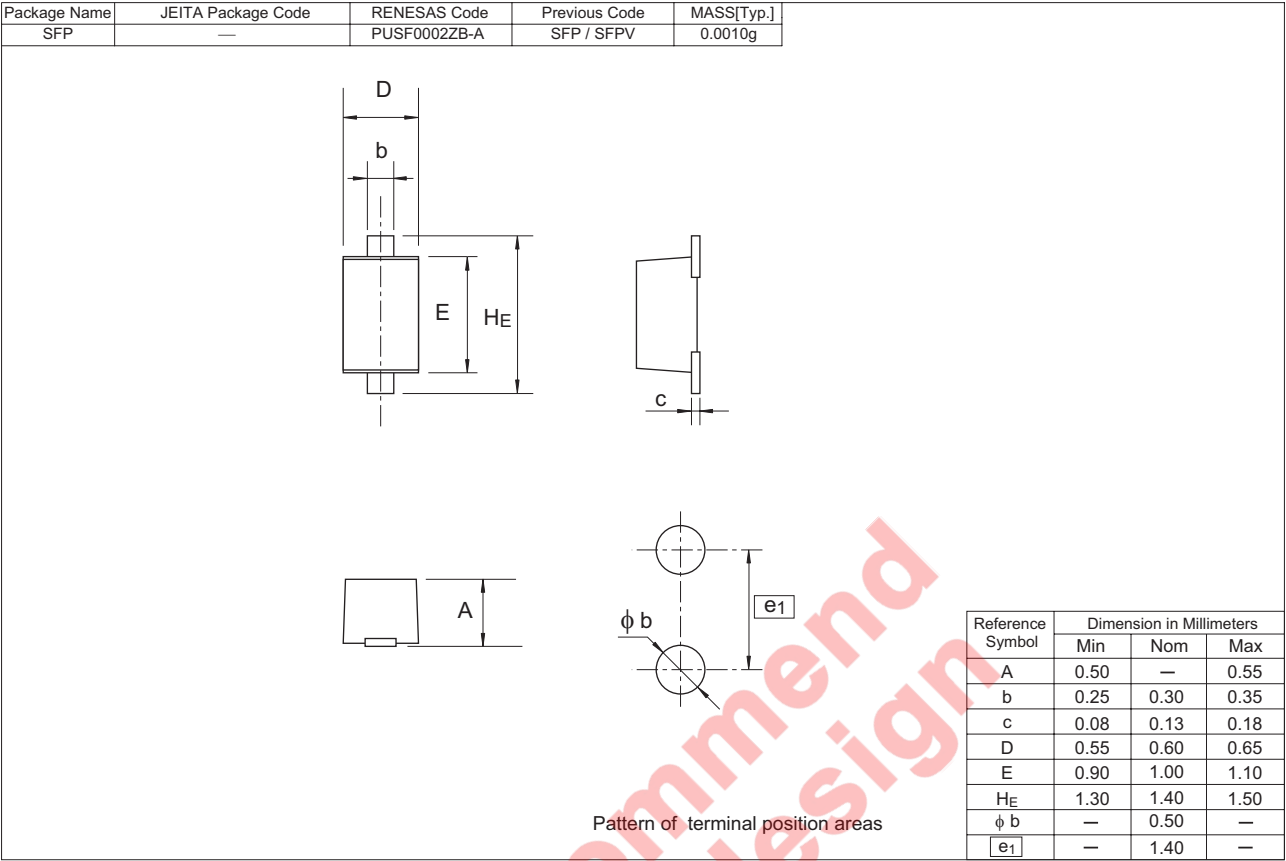


Fig.3 Series resistance vs. Reverse voltage

Package Dimensions



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